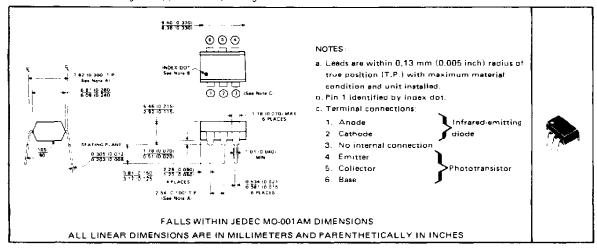
COMPATIBLE WITH STANDARD TTL INTEGRATED CIRCUITS

- Gallium Arsenide Diode Infrared Source Optically Coupled to a Silicon N-P-N Phototransistor
- **High Direct-Current Transfer Ratio**
- High-Voltage Electrical Isolation . . . 1.5-kV or 2.5-kV Rating
- Plastic Dual-In-Line Package
- High-Speed Switching: $t_r = 5 \mu s$, $t_f = 5 \mu s$ Typical

mechanical data

The package consists of a gallium arsenide infrared-emitting diode and an nipin silicon phototransistor mounted on a 6-lead frame encapsulated within an electrically nonconductive plastic compound. The case will withstand soldering temperature with no deformation and device performance characteristics remain stable when operated in high-humidity conditions. Unit weight is approximately 0.52 grams.

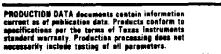


absolute maximum ratings at 25°C free-air temperature (unless otherwise noted)

Input-to-Output Voltage: TIL111
T(L114, T)L116, T)L117
Collector-Base Voltage
Collector-Emitter Voltage (See Note 1)
Emitter-Collector Voltage
Emitter Base Voltage
Input-Diode Reverse Voltage
Input Diode Continuous Forward Current at (or below) 25°C Free Air Temperature (See Note 2) 100 mA
Continuous Power Dissipation at (or below) 25°C Free-Air Temperature:
Infrared-Emitting Diode (See Note 3)
Phototransistor (See Note 4)
Total, Infrared-Emitting Diode plus Phototransistor (See Note 5)
Storage Temperature Range
Lead Temperature 1,6 mm (1/16 Inch) from Case for 10 Seconds

This value applies when the base emitter diode is open circuited

- Derate linearly to 100°C free-air temperature at the rate of 1.33 mA/ C
- Derate linearly to 100°C free air temperature at the rate of 2 mW°C.
 Derate linearly to 100°C free air temperature at the rate of 2 mW°C. 5. Denate linearly to 100°C free air temperature at the rate of 3.33 mW C





TIL111, TIL114, TIL116, TIL117 OPTOCOUPLERS

electrical characteristics at 25°C free-air temperature

	PARAMETER		AMETER TEST CONDITIONS		TIL111 TIL114			TIL116			TIL117			UNIT
					MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
VIBR)CBO	Collector-Base Breakdown Voltage		I _C = 10 μA, I _F = 0	1 _E = 0,	70			70			70			V
VIBR)CEO	Callector-Emitter Breakdown Voltage		I _C = 1 mA, I _F = 0	18 = O,	30			30			30			V
V(BR)EBO	Emitter-Base Breakdown Voltage		I _E = 10 μΑ, I _F = 0	I _C = 0,	7			7			7			V
^I R	Input Diode Static Reverse Current		V _H = 3 V				10			10			10	μΑ
	On-State Collector Current	Phototransistor	V _{CE} = 0.4 V, I _B = 0 V _{CE} = 10 V,	·	2	7								mA
¹ C(on)		Photodiode	i _B = 0 V _{CB} = 0.4 V,	I _F = 16 mA,	7	20		7	20		7	20		μΑ
¹ C(off)	Off-State Collector Current	Operation Phototransistor Operation	V _{CE} = 10 V. I _B = 0	IF = 0,		1	50		1	50	1	1	50	nA.
		Photodiode Operation	V _{CB} = 10 V, I _E = 0	lt = 0'		0 1	20		0.1	20		0.1	20	
hFE Fo	Transistor Static		V _{CE} = 5 V. I _F = 0		100	300					200	550		
	Transfer f		V _{CE} = 5 V, F = 0	Aپ 100 م ا				100	300					
VF	Input Diode Static Forward Voltage		1 _F = 16 mA		1	1.2	1.4		1.25	1.5	ļ	1.2	1.4	V
VCE(sat)	Collector-Emitter Saturation Voltage		I _C = 2 mA, I _B = 0	ic = 16 mA,		0.25	0.4							: :
			1 _C = 2.2 mA,	•					0.25	04				: v
			1 _C = 0.5 mA, 1 _B ÷ 0		<u> </u>			ļ				0.25	0 4	
⁷ 10	Input-to-Output Internal Resistance			kV for TIE111, kV for all others,	1011			1013			1011			23
Cio	Input to-Output Capacitance		V _{in-out} = 0, See Note 6	t = 1 MHz,		1	13	İ	1	1.3		1	1.3	ρF

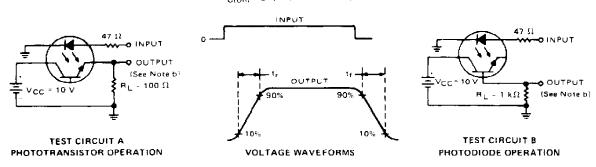
NOTE 6. These parameters are measured between both input diode leads shorted together and all the phototransistor leads shorted together.

switching characteristics at 25°C free-air temperature

	PARAMET	TER	TEST CONDITIONS		TIL111 TIL114			T1L116			T1L117		
					TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX]
1,	Rise Time	Phototransistor	$V_{CC} = 10 \text{ V}, \qquad I_{C(DD)} = 2 \text{ mA}.$ $R_1 = 100 \Omega_2$		5	10		5	10		5	10	
t j	Fall Time	Operation	See Test Circuit A of Figure 1		5	10		5	10		5	10	μS
t _r	Rise Time	Photodiode	$V_{CC} = 10 \text{ V}, I_{C(on)} = 20 \mu\text{A}$ $R_1 = 1 \text{k}\Omega,$	-	1			1			1		
tf	Fall Time	Operation	See Test Circuit B of Figure 1		1			1			1		μs

PARAMETER MEASUREMENT INFORMATION

Adjust amplitude of input pulse for: $I_{C(on)} = 2$ mA (Test Circuit A) or $I_{C(on)} = 20$ μ A (Test Circuit B)



- NOTES: a. The input waveform is supplied by a generator with the following characteristics: $Z_{\rm out}$ = 50 $\Omega_{\rm c}$ t, fig. 15 ns, duty cycle \approx 1%, $t_{\rm w}$ = 100 μs
 - b. The output waveform is monitored on an oscilloscope with the following characteristics: $t_{\rm r} \approx 12$ ns, $R_{\rm in} \approx 1$ M Ω , $C_{\rm in} \approx 20$ pF.

FIGURE 1-SWITCHING TIMES

TYPICAL CHARACTERISTICS

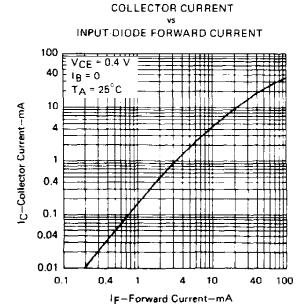


FIGURE 2

TIL111, TIL114

TIL116, TIL117

COLLECTOR CURRENT

vs

INPUT-DIODE FORWARD CURRENT

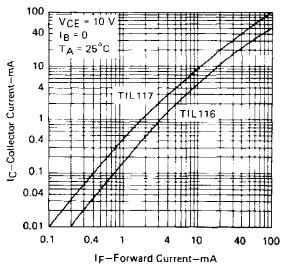
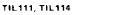


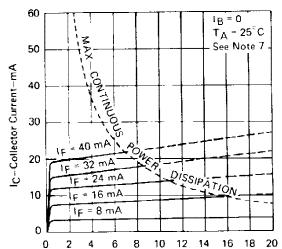
FIGURE 3

TYPICAL CHARACTERISTICS



COLLECTOR CURRENT vs

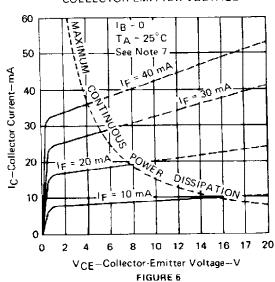
COLLECTOR EMITTER VOLTAGE



VCE-Collector-Emitter Voltage-V FIGURE 4

TIL117 COLLECTOR CURRENT

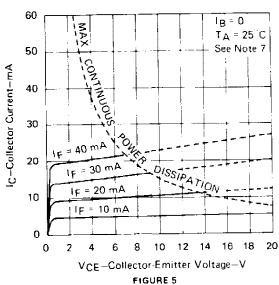
COLLECTOR-EMITTER VOLTAGE



TIL116

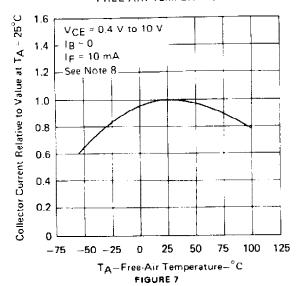
COLLECTOR CURRENT

COLLECTOR-EMITTER VOLTAGE



RELATIVE ON-STATE COLLECTOR CURRENT

FREE AIR TEMPERATURE



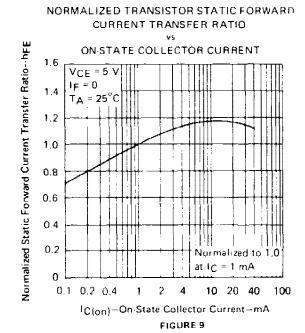
NOTES: 7. Pulse operation of input diode is required for operation beyond limits shown by dotted lines

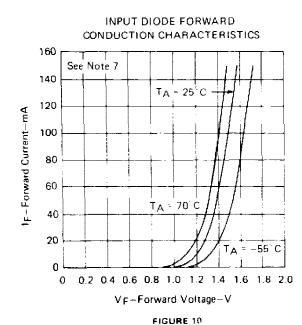
B. These parameters were measured using pulse techniques $|t_{W}| \approx 1$ ms, duty cycle $\leq 2\%$

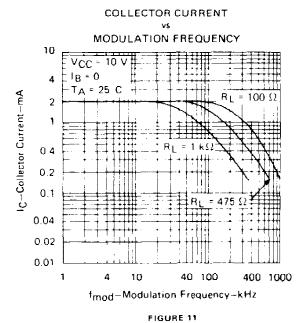
TYPICAL CHARACTERISTICS

OFF-STATE COLLECTOR CURRENT FREE-AIR TEMPERATURE 10 000 V_CE = 10 V 4 000 1B = 0 1F = 0 IC(oft) - Off-State Collector Current 1 000 400 100 40 10 4 0.4 0.1 0 10 40 50 60 70 80 TA- Free Air Temperature-"C

FIGURE 8







NOTE 7: These parameters were measured using pulse techniques, $t_{
m w}=1$ ms, duty cycle $\sim 2\%$

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